**Thermoelectric Module Specifications**

<table>
<thead>
<tr>
<th>Material Specifications (27 °C hot side temperature)</th>
<th>Material Specifications (50 °C hot side temperature)</th>
<th>Module material specifications are nominal values based on the hot-side temperature indicated. Thermoelectric material parameter tolerance is +/-10%.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Vmax (V)</td>
<td>16.1</td>
<td>In no case should the module temperature be allowed to exceed its maximum operation/storage temperature.</td>
</tr>
<tr>
<td>Imax (A)</td>
<td>3.6</td>
<td>Please review all product and technical information, Thermoelectric Module Mounting Procedure, parameter definitions, FAQ's, and ordering information posted on our website before purchasing or using this product.</td>
</tr>
<tr>
<td>Qmax (W)</td>
<td>36.0</td>
<td></td>
</tr>
<tr>
<td>DTmax (°C)</td>
<td>71</td>
<td></td>
</tr>
<tr>
<td>Operation/storage temperature</td>
<td>-40 °C to +80 °C</td>
<td></td>
</tr>
</tbody>
</table>

**Optional Features and Notes:**

- Width, A (mm) 30 +0.5/-0.2
- Width, B (mm) 30 +0.5/-0.2
- Height, H (mm) 3.6 ±0.05
- Flatness, F (mm) 0.02
- Parallelism, P (mm) 0.03
- Wire Size, WS (mm²) 0.35
- Wire Length, WL (mm) 120

Performance graphs include thermal resistance of substrates.

Add "P" to part number for sealing module with epoxy potting.

RoHS Compliant
Unpotted HP-127-1.0-1.3-71 at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice.

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Potted HP-127-1.0-1.3-71 at a hot-side temperature of 30 °C
Unpotted HP-127-1.0-1.3-71 at a hot-side temperature of 50 °C
Potted HP-127-1.0-1.3-71 at a hot-side temperature of 50 °C

Note: All specifications subject to change without notice.
Unpotted HP-127-1.0-1.3-71 at a hot-side temperature of 70 °C
Potted HP-127-1.0-1.3-71 at a hot-side temperature of 70 °C